

Title (en)

COOLING SYSTEM FOR AN ELECTRONIC SYSTEM

Title (de)

KÜHLSYSTEM FÜR EIN ELEKTRONISCHES SYSTEM

Title (fr)

SYSTEME DE REFROIDISSEMENT POUR SYSTEME ELECTRONIQUE

Publication

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Application

EP 22721062 A 20220407

Priority

- FR 2103557 A 20210407
- EP 2022059188 W 20220407

Abstract (en)

[origin: WO2022214570A1] The present invention relates to an electronic system module (3) that comprises a plurality of electrical and/or electronic components (5), at least one temperature control element (7) configured so as to adjust a temperature of at least one first electrical and/or electronic component (5) and placed opposite a portion of the first electrical and/or electronic component (5), said temperature control element (7) being placed between the first electrical and/or electronic component (5) and a second electrical and/or electronic component (5) adjacent to the first electrical and/or electronic component (5). The module (3) comprises at least one protective component (11) in which the temperature control element (7) is at least partially embedded, said protective component (11) being at least partially in contact with the plurality of electrical and/or electronic components (5).

IPC 8 full level

H01M 10/613 (2014.01); **B60L 58/26** (2019.01); **H01M 10/615** (2014.01); **H01M 10/625** (2014.01); **H01M 10/653** (2014.01); **H01M 10/6557** (2014.01); **H01M 10/6567** (2014.01); **H01M 50/204** (2021.01); **H01M 50/209** (2021.01); **H01M 50/213** (2021.01); **H01M 50/249** (2021.01); **H01M 50/264** (2021.01)

CPC (source: EP US)

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Citation (search report)

See references of WO 2022214570A1

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